

Atty Docket No. JCLA8533-D2

Serial No. 10/755,042

REMARKS**1. Present Status of the Application**

Upon this response, claims 30-40, 43-48, 52, 54-60, and 141-162 remain pending in the present application. More specifically, claims 30-40, 43-48, 52 and 54-60 are directly amended; claims 139 and 140 are canceled; claims 141-162 are newly added. It is believed that the foregoing amendments add no new matter to the present application.

2. Response To Objections/Rejections

Applicants respectfully traverse the rejections for at least the reasons set forth below.

Response To Claim 30

As amended, independent claim 30 is recited below:

30. A chip package structure comprising:
at least a die having a first active device and a second active device; and
a metal layer deposited over said die and extending to a place under which there is no die, wherein a signal is suited for being transmitted from said first active device to said second active device through said metal layer.

(emphasis added)

Applicants respectfully assert that the chip package claimed in claim 30 patentably distinguishes over the citations by Vu, by Miura, by Honda and by Shanefield.

Applicants teach that a metal layer deposited over a die and extending to a place under which there is no die, wherein a signal is suited for being transmitted from a first active device of

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the die to a second active device of the die through the metal layer, which is not taught, hinted or suggested by Vu, by Miura, by Honda and by Shanefield. Therefore, applicants consider that the above feature can not be anticipated in view of Vu's, Miura's, Honda's and Shanefield's devices.

For at least the foregoing reasons, applicants respectfully submit independent claim 30 patentably defines over the prior art references, and should be allowed. For at least the same reasons, dependent claims 31-40, 43-48, 52 and 54-60 patentably define over the prior art as well.

Response To Claim 141

As amended, independent claim 141 is recited below:

141. A chip package structure comprising:
a substrate;
at least a die joined with said substrate, and having a first active device and a second active device; and
a metal layer deposited over said die, wherein a signal is suited for being transmitted from said first active device to said second active device through said metal layer.

(emphasis added)

Applicants respectfully assert that the chip package claimed in claim 141 patentably distinguishes over the citations by Vu, by Miura, by Honda and by Shanefield.

Applicants teach that a metal layer deposited over a die, wherein a signal is suited for being transmitted from a first active device of the die to a second active device of the die through the metal layer., which is not taught, hinted or suggested by Vu, by Miura, by Honda and by

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Shanefield. Therefore, applicants consider that the above feature can not be anticipated in view of Vu's, Miura's, Honda's and Shanefield's devices.

For at least the foregoing reasons, applicants respectfully submit independent claim 141 patently defines over the prior art references, and should be allowed. For at least the same reasons, dependent claims 142-162 patently define over the prior art as well.

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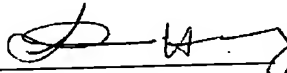
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CONCLUSION

For at least the foregoing reasons, it is believed that the pending claims 30-40, 43-48, 52, 54-60, and 141-162 are in proper condition for allowance. If the Examiner believes that a telephone conference would expedite the examination of the above-identified patent application, the Examiner is invited to call the undersigned.

Respectfully submitted,

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